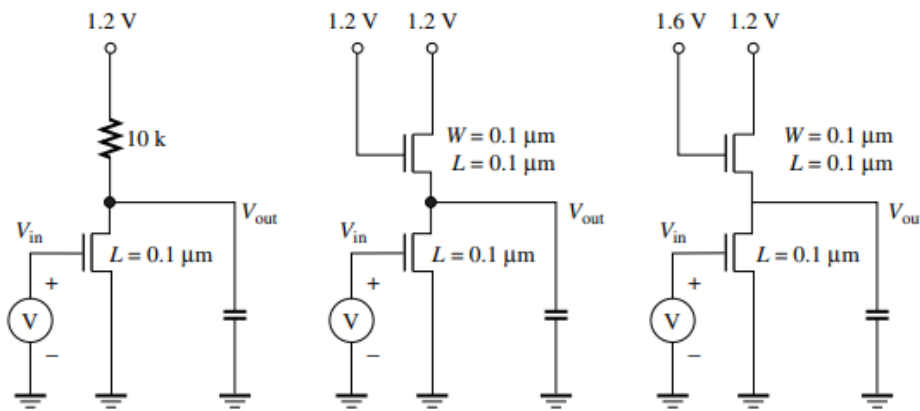


**UNIVERSITY OF BRITISH COLUMBIA**  
**DEPARTMENT OF ELECTRICAL AND COMPUTER ENGINEERING**

**ELEC 402: Introduction to VLSI Design**  
**Fall 2021**

**Assignment 3: The MOS Transistor / Cadence**  
**Due Date: Sunday, Oct 24 th (via Email)**

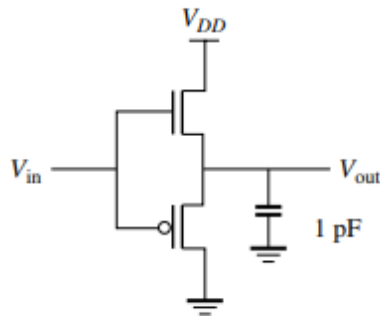
1. In the circuits of Figure, design the widths of the pull-down transistors so that  $V_{OL} = 0.1$  V. (All transistors are minimum size,  $L = 0.1 \mu\text{m}$ .) Explain the results. (15 points)



$$\mu_n = 270 \text{ cm}^2/\text{V}\cdot\text{s}, \quad C_{ox} = 1.0 \text{ } \mu\text{F}/\text{cm}^2, \quad V_{T0} = 0.4 \text{ V}, \quad V_{DD} = 1.2 \text{ V}$$

$$E_{CN}L = 0.6 \text{ V}, \quad v_{sat} = 8 \times 10^6 \text{ cm/s}, \quad \gamma = 0.2 \text{ V}^{1/2}, \quad 2|\phi_F| = 0.88 \text{ V}$$

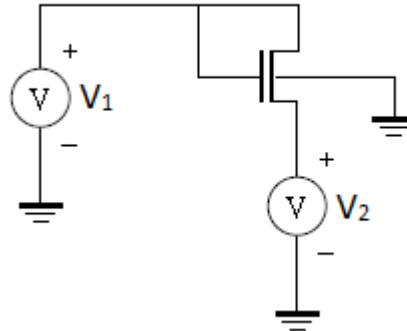
2. (a) What is the intended function of the circuit shown in Figure ? What is the output swing?



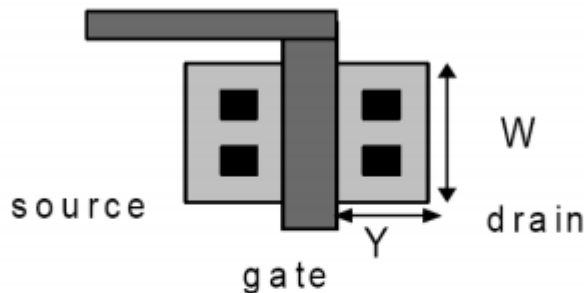
- (b) Draw the dc voltage transfer characteristic of the above gate. Label  $V_{OL}$  and  $V_{OH}$ , and any other interesting values in the VTC. Since the gate has hysteresis, be sure to handle both the rising and falling cases.
- (c) What is the gain of the circuit? Is this a valid gate (i.e., does it have the needed noise rejection properties)?
- (d) Use CAD to validate your solution by plotting the VTC (20 points)

- For CAD simulation in Q2 assume  $V_{DD} = 0.9$  V, and use two fingers per transistor.

3. Figure shows a circuit used to measure the effective value of body effect factor ( $\gamma$ ) (by measuring  $V_T$  at different source voltages) and channel length modulation factor ( $\lambda$ ) (by measuring  $I_d$  at different  $V_{ds}$  values). Assume in formula for threshold voltage (slide 7 lecture set 4 – MOS basics),  $2\phi_F = 0.88$  V, and calculate  $V_{T0}$ ,  $\gamma$ , and  $\lambda$  for a device with 2 fingers. Can you justify the value of  $\gamma$  for the FinFET device you are simulating? Attach your CAD netlist, graphs and measurement data to your answers (25 points)



4. Consider the layout in the figure below implemented in a 180nm technology. Assume that the transistor has  $W=900\text{nm}$ ,  $L=180\text{nm}$  and a source/drain dimension  $Y=800\text{nm}$  and a lateral diffusion of  $22\text{nm}$ . Let  $t_{ox} = 40$  Å (Angstroms). ( 12 points)



- Compute the worst case gate capacitance per unit width,  $C_g$ , in units of fF/um. Estimate  $C_{gs}$ ,  $C_{gd}$  and  $C_{gb}$  in linear, saturation and cutoff, including overlap effects.
  - If  $N_A = 3 \times 10^{16}/\text{cm}^3$  and  $N_D = 3 \times 10^{19}/\text{cm}^3$ ,  $x_j = 300\text{nm}$ , compute the worst-case capacitance value per unit width,  $C_j$ , in units of fF/um.
  - Compute the drain junction capacitance for the following cases ( $m=0.5$ ):
    - $V_D = 1.8\text{V}$ ,  $V_B = 0\text{V}$
    - $V_D = 0\text{V}$ ,  $V_B = 0\text{V}$
5. A CMOS inverter in 45 nm technology has a pull-up device that is  $8\lambda:2\lambda$  and a pull-down device that is  $4\lambda:2\lambda$ . It drives four identical inverters at its output. Compute the inverter delay (use  $C_g = 2$  fF/um) and assume a ramp input. Re-calculate the delay if we have a chain of 4 inverters, i.e. 4 inverters in series (13 pts) Note:  $2\lambda = 45\text{nm}$